PCN Number:	20151217000	**PCN Date:**	12/18/2015
Title:	Qualification of DMOS6 as an additional Wafer Fab Site option for select devices in C021 Technology		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	3/18/2016	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This change notification is to announce the addition of DMOS6 as an additional Wafer Fab site option for the products listed in the product affected section of this document.

Current Wafer Fab Site	Process	Wafer Diameter
TSMC-F14	C021	300mm

Additional Fab Site	Process	Wafer Diameter
DMOS6	C021	300mm

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
TSMC-F14	T14	TWN	Tainan City

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
DMOS6	DM6	USA	Dallas

Sample product shipping label (not actual product label)

Product Affected Group:			
CC2560ANPYFVR	CC2564NSRVMT	CC2564YFVR	CC2567YFVR
CC2560ARVMR	CC2564NSYFVR	CC2564YFVT	CC2567YFVT
CC2560ARVMT	CC2564NYFVR	CC2567NSYFVR	CC2568YFVR
CC2560AYFVR	CC2564RVMR	CC2567RVMR	CC2569RVMR
CC2560AYFVT	CC2564RVMT	CC2567RVMT	CC2569RVMT
CC2564NSRVMR			

Qualification Report

Fab Transfer for C021.M Orca devices to DMOS6 for QFN and WCSP Packages

Qualification Approved: 12/17/2015

Product Attributes

	Qual Device #1: BL6450QVRM	Qual Device #2: XCC2567YFVT	Supporting QBS #3: BL6450QVRM
Wafer Fab Site	DMOS6	DMOS6	TSMC-F14
Wafer Fab Process	C021.M	C021.M	C021.M
Die Size (mm)	2.957 X 3.294	2.957 X 3.294	2.957 X 3.294
Assembly Site	AMKOR P1	CLARK AT	AMKOR P1
Package Family	VQFN	WCSP	VQFN
Package Designator	RVM	YFV	RVM
Package Size (mils)	314.96 X 314.96	116.42 X 129.68	314.96 X 314.96
Pin Count	76	54	76
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0

- QBS: Qual By Similarity
- Qual Device BL6450Q QFN is qualified at LEVEL3-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device #1: BL6450QVRM	Qual Device #2: XCC2567YFVT	Supporting QBS #3: BL6450QVRM
THB	Temperature Humidity Bias 85C/85% RH	168, 600, 1000 Hours	2/154/0 & QBS to #3	3/86/0	2/154/0
UHAST	Unbiased HAST 110C/85% RH	264 Hours	3/231/0	N/A	N/A
UHAST	Unbiased HAST 130C/85% RH	96 Hours	N/A	3/230/0	N/A
TC	Temperature Cycle -55/125C	1000 Cycles	3/231/0	3/230/0	N/A
HTSL	High Temperature Storage Life 150C	1000 Hours	1/45/0 & QBS to #3	3/231/0	3/231/0
HTOL	High Temperature Operating Life 125C	1000 Hours	3/231/0	QBS to #1	N/A
ELFR	Early Life Failure Rate 125C	168 Hours	3/2400/0	QBS to #1	N/A
HBM	ESD - HBM	500V	1/3/0	1/3/0	N/A
CDM	ESD - CDM	250 V	1/3/0	1/3/0	N/A
LU	Latchup 90C	100mA	1/3/0	QBS to #1	N/A
MQ	Manufacturability	Per Site Specifications	Pass	Pass	N/A

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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